SYSTEM START-UP:

1. Don’t forget to login into your FOM account and login to the tool.
2. Turn ON power to the oven using the breaker located on the back, left corner.
3. Press green Power On button
4. Turn ON vacuum pump located behind oven on the floor.

VACUUM BAKE:

1. Turn HMDS/NH₃ valve to HMDS position (located behind glass cylinder, short end of knob indicates valve selection)
2. Select 4 on the Thumbwheel.
3. Set temperature for front/rear zones. Press and hold SET BUTTON (far left), set temperature to desired setting.

**NOTE:** Oven must be at set temperature before beginning processing.

**Front Zone:** 20-160°C  
**Rear Zone:** 20-160°C

4. Press S.P. on the controller and check each set point.

Recommended Settings:

- **Set point 1** (Display Set Point) 600 Torr
- **Set point 2** (Set Point 2) 10 Torr
- **Set point 3** (Alarm 3 Low Limit) 1 Torr
- **Set point 4** no recommendation

Press S.P. to exit programming mode.
5. Using the touch screen press GOTO Alarms Panel
   GOTO Process Variables

   To change, touch screen button for variable, enter number, press Enter, and then press Done.
   Recommended Process Variables:
   Number of dehydration cycle purges: 3
   Number of exit cycle purges: 1
   IR Wafer Warm Up Delay: 0
   Process duration: Process dependent

7. Press GOTO OPERATOR PANEL.

8. Load Samples.

9. When oven has stabilized at set temperature, press START.

10. When Process is complete Shutdown oven.

SHUTDOWN:

1. Turn OFF breaker on back of oven.
2. Turn OFF vacuum pump.
3. Logout from the tool in your FOM account.
VAPOR PRIME USING YES OVEN SOP

Purpose: To prepare the surface of a wafer for photoresist application by coating with HMDS primer.

YES System Start-up:

Log in to the tool by using FOM, it will turn on vacuum pump.

Vapor Prime:

1. Turn HMDS/NH₃ valve to HMDS position (located behind glass cylinder, short end of knob indicates valve selection)
2. Select 1 on the Thumbwheel.
3. Press S.P. on the controller and check each set point

   Recommended Settings

   | Set point 1 (Display Set Point) | 600 Torr  |
   | Set point 2 (Set Point 2)       | 10 Torr   |
   | Set point 3 (Alarm 3 Low Limit) | 1 Torr    |
   | Set point 4                    | no recommendation |

4. Using the touch screen press:

   GOTO Alarms Panel
   GOTO Process Variables
5. Enter Process Variables

   Recommended Process Variables:
   - Number of dehydration cycle purges: 3
   - Number of exit cycle purges: 5
   - Process duration: 300 seconds

6. Press GOTO OPERATOR PANEL

7. Load samples

8. When oven has stabilized at set temperature, press START

9. When process is complete, acknowledge the alarm by hitting reset button on the touchscreen.

   Total time for the recommended process is approximately 31 minutes.

Shutdown:

Don’t forget to logoff from the tool using FOM, which will turn OFF the vacuum pump.
**Purpose:** To convert image from positive to negative image with positive photoresist.

**SYSTEM START-UP**

1. Log in to the tool by using FOM, it will turn **ON** the vacuum pump.

**IMAGE REVERSAL:**

3. Turn HMDS/NH$_3$ valve to NH$_3$ (located behind glass cylinder, short end of knob indicates valve selection)
4. Select **2** on the Thumbwheel.
5. Set temperature for front/rear zones. Press and hold **SET BUTTON** (far left), set temperature to desired setting.

   **NOTE:** Oven must be at set temperature before beginning processing.

**Front Zone:** 90°C  
**Rear Zone:** 90°C

6. Press **S.P.** on the controller and check each set point.

   **Recommended Settings:**

   **Set point 1:** (Display Set Point) 600 Torr  
   **Set point 2:** (Set Point 2) 100 Torr  
   **Set point 3:** (Alarm 3 Low Limit) 1 Torr  
   **Set point 4:** 500 Torr

7. Using the touch screen press:

   **GOTO** Alarms Panel
GOTO Process Variables

8. Enter Process Variables
Recommended Process Variables:

Number of dehydration cycle purges: 3
Number of exit cycle purges: 5
IR Wafer Warm Up Delay: 10
Process duration: 2700 seconds (45 min)

9. Press GOTO OPERATOR PANEL

10. Load Samples

11. When oven has stabilized at set temperature, press START

12. After process is done, perform flood exposure using ABM
Recommended parameters:

1813 12 sec
1827 25 sec
SPR220 60 sec

13. Develop

NOTE: Total cycle time for the recommended process is approximately 90 minutes.

SHUTDOWN

14. Don’t forget to logoff from the tool using FOM.